Package Type Weight of Package (grams)	SOT-23 8.70E-03	Note: All weight has been calculated based on specified target or average values for a given material or process. Actual device weight may vary slightly.					
Component	Material	Weight in grams	Substance in material	Wt% in component	Weight of substance in milligrams	Wt% in finished product	Parts per Million
Lead Frame	Metal alloy	2.37E-03				27.23	272279
			Fe	56.05	1.33	15.26	152613
			Ni	42.00	1.00	11.44	114357
			Mn	0.80	0.02	0.22	2178
			Co	0.50	0.01	0.14	1361
			Si	0.30	0.01	0.08	817
			Ag (DP plate)	0.35	0.01	0.10	953
Encapsulation	Epoxy	6.06E-03				69.62	696208
			Silica	73.10	4.43	50.89	508928
			Resin	25.00	1.52	17.41	174052
			Sb_2O_3	0.10	0.01	0.07	696
			Br	1.80	0.11	1.25	12532
Plating	Solder	2.06E-04				2.37	23666
			Sn	85.00	0.18	2.01	20116
			Pb	15.00	0.03	0.35	3550
Chip	Silicon	4.84E-05				0.56	5560
			Si	99.00	0.05	0.55	5505
Die Attach	Eutectic						
Wire Bond	Gold Wire	1.99E-05				0.23	2286
			Au	99.99	0.02	0.23	2286

Environmental Statement Disclaimer

The information provided in this environmental statement is, to our knowledge, correct as of the date indicated on this page. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.